*** Material Composition - nRF51422-CDAB**

Material	Purpose	Substance Composition	CAS Number	Weight by mg	% weight of substance per Homogenous material	PPM	% weight of substance per package
Polybenzoxazole1	**Dielectric**	Polyamide & Gamma-butyrolactone (75~95%)	----------	0.08732	100%	8416	0.842%
Polybenzoxazole2	**Dielectric**		----------	0.08254	100%	7954	0.795%
RDL Seed Layer	**Seed Layer**	Ti	7440-32-6	0.00031	3.93%	30	0.003%
	Seed Layer	W	7440-33-7	0.00277	35.40%	267	0.027%
	Seed Layer	Cu	7440-50-8	0.00474	60.67%	457	0.046%
Copper	**Interconnect**	Cu	7440-50-8	0.09487	100%	9143	0.914%
UBM Seed Layer	**Seed Layer**	Ti	7440-32-6	0.00013	3.93%	12	0.001%
	Seed Layer	W	7440-33-7	0.00113	35.40%	108	0.011%
	Seed Layer	Cu	7440-50-8	0.00193	60.67%	186	0.019%
Copper	**UBM**	Cu	7440-50-8	0.08677	100%	8363	0.836%
Solder Ball	**Interconnect**	Sn	7440-31-5	1.23004	95.50%	118545	11.855%
	Interconnect	Ag	7440-22-4	0.05152	4.00%	4965	0.497%
	Interconnect	Cu	7440-50-8	0.00644	0.50%	621	0.062%
Die	**Circuit**	Si	7440-21-3	8.30570	100%	800462	80.046%
Top Surface Laminate	**Mark Surface**	Proprietary	----------	0.41994	100%	40472	4.047%
			Package Weight (mg):	**10.38**		**% Total:**	**100%**